

# **Voltage Detector**

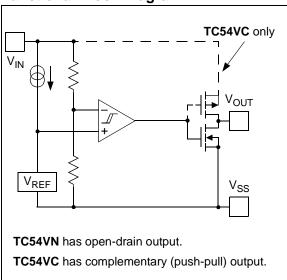
## Features:

- ±2.0% Detection Thresholds
- Small Packages: 3-Pin SOT-23A, SOT-89, and TO-92
- Low Current Drain: 1 µA, typical
  Wide Detection Range: 1.1V to 6.0V
- Wide Operating Voltage Range: 0.7V to 10V

## **Applications:**

- · Battery Voltage Monitoring
- Microprocessor Reset
- System Brown-Out Protection
- · Switching Circuit in Battery Backup
- · Level Discriminator

## **Functional Block Diagram**

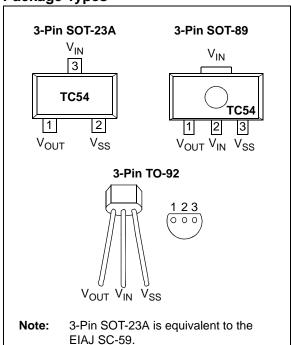


## **General Description:**

The TC54 series are CMOS voltage detectors especially well-suited for battery-powered applications because of their extremely low 1  $\mu$ A operating current and small surface-mount packaging. Each part is laser-trimmed to the desired threshold voltage, which can be specified from 1.4V to 6.0V with a 2% tolerance.

The TC54 is available with either an open-drain or complementary output stage. During operation, the output (V<sub>OUT</sub>) remains in the logic-high state as long as V<sub>IN</sub> is greater than the specified threshold voltage (V<sub>DET</sub>  $^-$ ). When V<sub>IN</sub> falls below V<sub>DET</sub>  $^-$ , the output is driven to a logic-low. V<sub>OUT</sub> remains low until V<sub>IN</sub> rises above V<sub>DET</sub>  $^-$  by an amount V<sub>HYST</sub>, when it resets to a logic-high state.

## **Package Types**



## **Device Features**

Device	Output		Reset Delay	Std. Trip Points <sup>(1)</sup> (typical)
Device	Туре	State	Reset Delay	Std. Trip Politis* (typical)
TC54VN	Open-Drain	Active Low	No	1.4V, 2.1V, 2.7V, 2.9V
TC54VC	Push-Pull	Active Low	No	3.0V, 4.2V, 4.3V

Note 1: Custom Trip Points available. Minimum order requirement. Information available upon request.

# 1.0 ELECTRICAL CHARACTERISTICS

## **Absolute Maximum Ratings †**

Input Voltage+12\
Output Current50 mA
Output Voltage: CMOS $(V_{SS} - 0.3V)$ to $(V_{IN} + 0.3V)$
Open-Drain(V <sub>SS</sub> – 0.3V) to 12\
Power Dissipation (T <sub>A</sub> ≤ 70°C):
3-Pin SOT-23A240 mV
3-Pin SOT-89500 mV
3-Pin TO-92300 mV
Operating Temperature Range40°C to +85°C
Storage Temperature Range65°C to +150°C

† Notice: Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions above those indicated in the operation sections of the specifications is not implied. Exposure to Absolute Maximum Rating conditions for extended periods may affect device reliability.

## **DC CHARACTERISTICS**

Electrical Specifications: Unless otherwise noted, T <sub>A</sub> = +25°C.						
Parameter	Symbol	Min.	Тур.	Max.	Units	Test Conditions
Operating Voltage	V <sub>IN</sub>	0.7	_	10.0	V	(V <sub>DET</sub> −) ≥ 1.6V
		0.7	_	6.0	V	(V <sub>DET</sub> −) < 1.6V
Quiescent Current	I <sub>SS</sub>	_	0.8	2.7	μΑ	V <sub>IN</sub> = 2.0V
		_	0.9	3.0		V <sub>IN</sub> = 3.0V
		_	1.0	3.2		V <sub>IN</sub> = 4.0V
		_	1.1	3.6		V <sub>IN</sub> = 5.0V
Threshold Voltage	V <sub>DET</sub> -	1.37	1.4	1.43	V	TC54VX14
(Note 1)		2.06	2.1	2.14		TC54VX21
		2.65	2.7	2.75		TC54VX27
		2.84	2.9	2.96		TC54VX29
		2.94	3.0	3.06		TC54VX30
		4.12	4.2	4.28		TC54VX42
		4.21	4.3	4.39		TC54VX43
		N.M-2%	N.M	N.M+2%		TC54VXNM (Note 2)
Hysteresis Voltage	$V_{HYST}$	28	70	112	mV	V <sub>DET</sub> = 1.4V (typical)
		42	105	168		V <sub>DET</sub> = 2.1V (typical)
		54	135	216		V <sub>DET</sub> = 2.7V (typical)
		58	145	232		V <sub>DET</sub> = 2.9V (typical)
		60	150	240		V <sub>DET</sub> = 3.0V (typical)
		84	210	336		V <sub>DET</sub> = 4.2V (typical)
		86	215	344		V <sub>DET</sub> = 4.3V (typical)
		Q-60%	Q	Q+60%		$V_{DET} = (20*Q)V \text{ (typical) (Note 2)}$
Output Current	I <sub>OUT</sub>	3.0	7.7	_	mA	$V_{OL} = 0.5V, V_{IN} = 2.0V$
		5.0	10.1	_		$V_{OL} = 0.5V, V_{IN} = 3.0V$
		6.0	11.5	_		$V_{OL} = 0.5V, V_{IN} = 4.0V$
		7.0	13.0	_		$V_{OL} = 0.5V, V_{IN} = 5.0V$
			-10.0	-2.0		TC54VC Only: $V_{OH} = V_{IN} - 2.1V, V_{IN} = 8.0V$
Tempco of (V <sub>DET</sub> -)	T <sub>C</sub> (V <sub>DET</sub> -)	_	±100	_	ppm/°C	-40°C ≤ T <sub>A</sub> ≤ 85°C
Delay Time	t <sub>DLY</sub>	_	_	0.2	ms	$V_{DET} - \rightarrow V_{OUT}$ inversion

Note 1: For other voltage options, please contact your regional Microchip sales office.

<sup>2:</sup> Represents all other custom Threshold Voltage options.

# **TEMPERATURE SPECIFICATIONS**

Electrical Characteristics: Unless otherwise indicated, all limits are specified for: $V_{DD} = +1.8V$ to $+5.5V$ , $V_{SS} = GND$ .						
Parameters	Sym.	Min.	Тур.	Max.	Units	Conditions
Temperature Ranges						
Operating Temperature Range	T <sub>A</sub>	-40	_	+85	°C	
Storage Temperature Range	T <sub>A</sub>	-65	_	+150	°C	
Thermal Package Resistances						
Thermal Resistance, 3L-SOT-23A	$\theta_{JA}$	_	308	_	°C/W	
Thermal Resistance, 3L-SOT-89	$\theta_{JA}$	_	131.7	_	°C/W	
Thermal Resistance, 3L-TO-92	$\theta_{JA}$	_	146	_	°C/W	

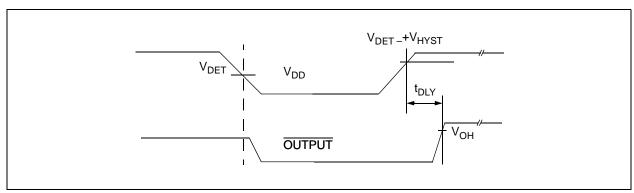


FIGURE 1-1: Timing Diagram.

## 2.0 PIN DESCRIPTIONS

The descriptions of the pins are listed in Table 2-1.

TABLE 2-1: PIN FUNCTION TABLE

TC54		Symbol	Description	
SOT-23A	SOT-89	TO-92	Эушрог	Description
1	1	1	V <sub>OUT</sub>	Digital Output
3	2	2	V <sub>IN</sub>	Analog Input
2	3	3	V <sub>SS</sub>	Ground Terminal
_	Tab	_	V <sub>IN</sub>	Analog Input

# 2.1 Digital Output (V<sub>OUT</sub>)

 $V_{OUT}$  goes low when  $V_{IN}$  drops below  $V_{DET}-$  and returns high when  $V_{IN}$  rises above  $V_{DET}-+V_{HYST}\!.$  (See Figure 3-1).

# 2.2 Analog Input (V<sub>IN</sub>)

 $\ensuremath{V_{\text{IN}}}$  can be used for power supply monitoring or a voltage level that requires monitoring.

# 2.3 Ground Terminal (V<sub>SS</sub>)

 $\mbox{$V_{\rm SS}$}$  provides the negative reference for the analog input voltage. Typically, the circuit ground is used.

## 3.0 DETAILED DESCRIPTION

In normal steady-state operation when  $V_{IN} > V_{DET}$ —, the output will be at a logic-high (see Figure 3-1). In the case of the TC54VN, this is an open-drain condition. If the input falls below  $V_{DET}$ —, the output will pull down (Logic 0) to  $V_{SS}$ . Generally,  $V_{OUT}$  can pull down to within 0.5V of  $V_{SS}$  at rated output current and input voltage. (See Section 1.0 "Electrical Characteristics").

The output (V<sub>OUT</sub>) will stay valid until the input voltage falls below the minimum operating voltage (V<sub>INMIN</sub>) of 0.7V. Below this minimum operating voltage, the output is undefined. During power-up (or anytime V<sub>IN</sub> has fallen below V<sub>INMIN</sub>), V<sub>OUT</sub> will remain undefined until V<sub>IN</sub> rises above V<sub>INMIN</sub>. When this occurs, the output will become valid. V<sub>OUT</sub> will be in its Active-low state, while V<sub>INMIN</sub> < V<sub>IN</sub> < V<sub>DET</sub>+ (therefore, V<sub>DET</sub>+ = V<sub>DET</sub>- + V<sub>HYST</sub>). If the input rises above V<sub>DET</sub>+, the output will assume its Inactive state (high for TC54VC, open-drain for TC54VN).

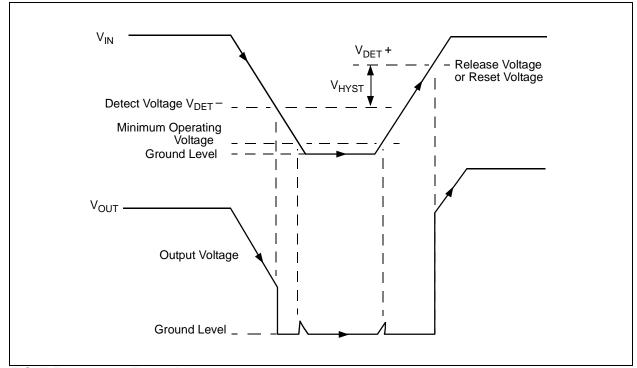


FIGURE 3-1: Timing Diagram.

## 4.0 APPLICATIONS INFORMATION

# 4.1 Modifying the Trip Point, V<sub>DET</sub> -

Although the TC54 has a pre-programmed  $V_{DET}$ –, it is sometimes necessary to make adjustments during prototyping. This can be accomplished by connecting an external resistor divider to a TC54, which has a  $V_{DET}$ – lower than that of  $V_{SOURCE}$  (Figure 4-1).

To maintain detector accuracy, the bleeder current through the divider should be significantly higher than the 1  $\mu\text{A}$  operating current required by the TC54. A reasonable value for this bleeder current is 100  $\mu\text{A}$  (100 times the 1  $\mu\text{A}$  required by the TC54). For example, if  $V_{DET}=2V$  and the desired trip point is 2.5V, the value of  $R_1+R_2$  is 25 k $\Omega$  (2.5V/100  $\mu\text{A}$ ). The value of  $R_1+R_2$  can be rounded to the nearest standard value and plugged into the equation of Figure 4-1 to calculate values for  $R_1$  and  $R_2$ . 1% tolerance resistors are recommended.

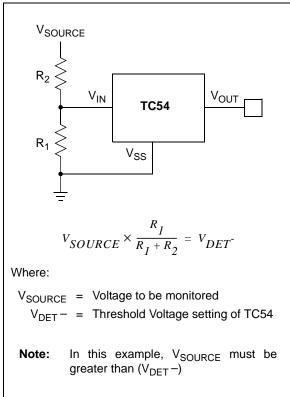


FIGURE 4-1: Modify Trip-point of the TC54 using External Resistor Divider.

## 4.2 Other Applications

Low operating power and small physical size make the TC54 series ideal for many voltage detector applications, such as those shown in Figures 4-2, 4-3 and 4-4. Figure 4-2 shows a low-voltage gate drive protection circuit that prevents the overheating of the logic-level MOSFET due to insufficient gate voltage. When the input signal is below the threshold of the TC54VN, its output grounds the gate of the MOSFET. Figure 4-3 and Figure 4-4 show the TC54 in conventional voltage monitoring applications.

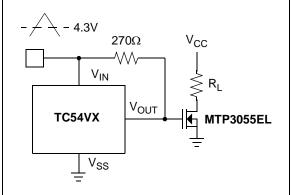


FIGURE 4-2: MOSFET Low Drive Protection.

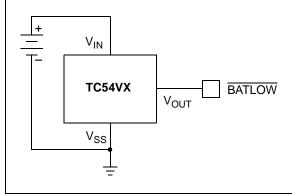


FIGURE 4-3: Battery Voltage Monitor.

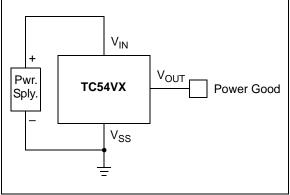
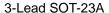
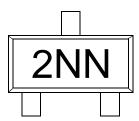


FIGURE 4-4: Power Good Monitor.

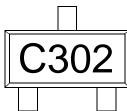
#### 5.0 PACKAGING INFORMATION

#### 5.1 **Package Marking Information**





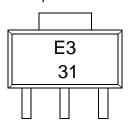
Example



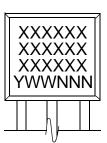
3-Lead SOT-89



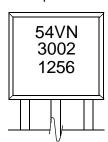
Example



3-Lead TO-92



Example



Legend: XX...X Customer-specific information

> Year code (last digit of calendar year) ΥY Year code (last 2 digits of calendar year) WW Week code (week of January 1 is week '01')

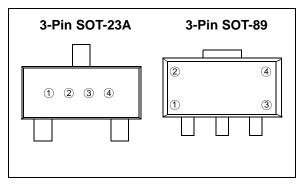
Alphanumeric traceability code NNN

Pb-free JEDEC® designator for Matte Tin (Sn) (e3)

This package is Pb-free. The Pb-free JEDEC designator (@3)

can be found on the outer packaging for this package.

Note: In the event the full Microchip part number cannot be marked on one line, it will be carried over to the next line, thus limiting the number of available characters for customer-specific information.



① represents output configuration (CMOS or Nch) and first integer of voltage

Ex: CMOS 3.x = (D) () ()

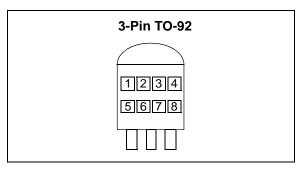
Symbol	Output	Voltage
В	CMOS	1.
С	CMOS	2.
D	CMOS	3.
E	CMOS	4.
F	CMOS	5.
Н	CMOS	6.
I	CMOS	7.
Symbol	Output	Voltage
Symbol L	Output N-Channel	Voltage 1.
Symbol L M	•	
L	N-Channel	1.
L M	N-Channel N-Channel	1.
L M N	N-Channel N-Channel N-Channel	1. 2. 3.
L M N P	N-Channel N-Channel N-Channel N-Channel	1. 2. 3. 4.

2 represents first decimal of output voltage (0-9)

Ex: CMOS 3.x = ① ④ 〇 〇

Symbol	Voltage	Symbol	Voltage
0	.0	6	.6
1	.1	7	.7
2	.2	8	.8
3	.3	9	.9
4	.4		
5	.5		

 $\ensuremath{\mathfrak{B}}$  and  $\ensuremath{\mathfrak{A}}$  represent assembly lot code



①, ② and ③ = 54X (fixed)

④ represents output configuration (CMOS or N-Ch) Ex: CMOS 3.x = © ○ ○ ○

Symbol	Output
С	CMOS
N	N-Channel

⑤ represents first integer of detect voltage

Symbol	Voltage
2	2.
3	3.
4	4.
5	5.
6	6.

6 represents first decimal of detect voltage

Symbol	Voltage	Symbol	Voltage
0	.0	5	.5
1	.1	6	.6
2	.2	7	.7
3	.3	8	.8
4	.4	9	.9

7 represents the output delay time

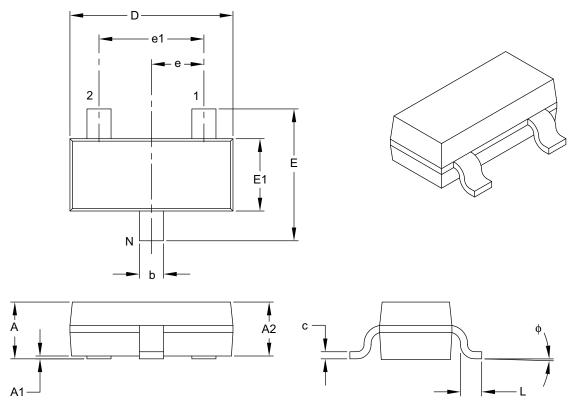
Symbol	Delay Time
0	No Delay

® represents the device accuracy

Symbol	Accuracy
1	±1.0% (custom)
2	±2.0% (standard)

# 3-Lead Plastic Small Outline Transistor (CB) [SOT-23A]

**Note:** For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



	Units	MILLIMETERS			
	Dimension Limits	MIN	NOM	MAX	
Number of Pins	N	3			
Lead Pitch	е		0.95 BSC		
Outside Lead Pitch	e1		1.90 BSC		
Overall Height	A	0.89	_	1.45	
Molded Package Thickness	A2	0.90	_	1.30	
Standoff	A1	0.00	_	0.15	
Overall Width	E	2.10	_	3.00	
Molded Package Width	E1	1.20	1.20 –		
Overall Length	D	2.70	2.70 –		
Foot Length	L	0.15	0.15 –		
Foot Angle	ф	0°	0° –		
Lead Thickness	С	0.09	_	0.26	
Lead Width	b	0.30	_	0.51	

## Notes:

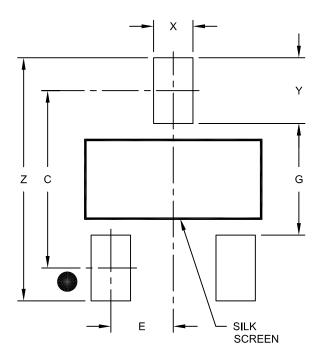
- 1. Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.127 mm per side.
- 2. Dimensioning and tolerancing per ASME Y14.5M.

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing C04-130B

# 3-Lead Plastic Small Outline Transistor (CB) [SOT-23A]

**Note:** For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



**RECOMMENDED LAND PATTERN** 

	MILLIMETERS			
Dimension	MIN	NOM	MAX	
Contact Pitch	Е	0.95 BSC		
Contact Pad Spacing	ontact Pad Spacing C			
Contact Pad Width (X3)	Х			0.60
Contact Pad Length (X3)	Υ			1.00
Distance Between Pads	G	1.70		·
Overall Width	Z			3.70

## Notes:

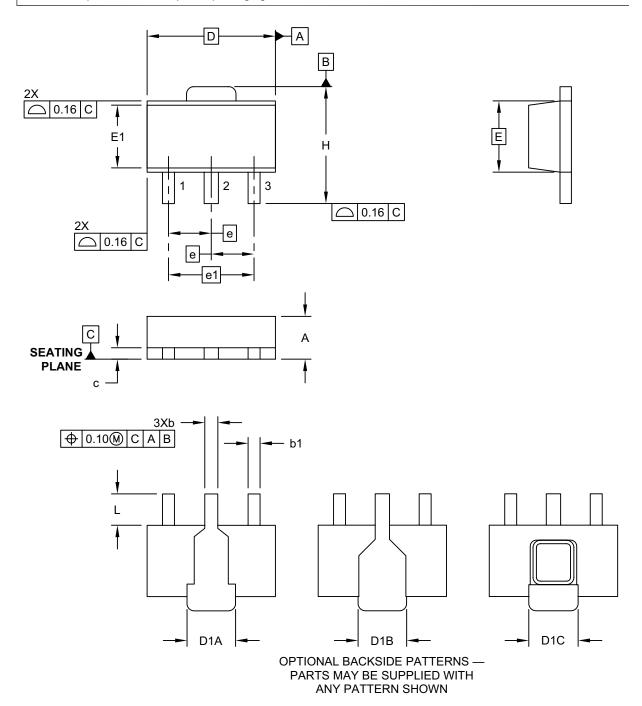
1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2130A

# 3-Lead Plastic Small Outline Transistor (MB) - [SOT-89]

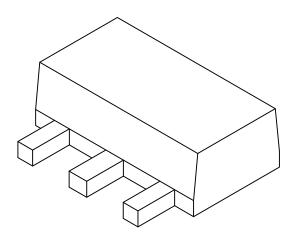
**Note:** For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Microchip Technology Drawing C04-029C Sheet 1 of 2

# 3-Lead Plastic Small Outline Transistor (MB) - [SOT-89]

**Note:** For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



	MILLIMETERS						
Dimension	MIN	NOM	MAX				
Number of Leads	N	3					
Pitch	е		1.50 BSC				
Outside Lead Pitch	e1		3.00 BSC				
Overall Height	Α	1.40	1.50	1.60			
Overall Width	Н	3.94	3.94 4.10 4				
Molded Package Width at Base	Е	2.50 BSC					
Molded Package Width at Top	E1	2.13					
Overall Length	D	4.50 BSC					
Tab Length (Option A)	D1A	1.63	1.63 1.73				
Tab Length (Option B)	D1B	1.40	1.40 1.60				
Tab Length (Option C)	D1C	1.62	1.62 1.73				
Foot Length	L	0.79	1.10	1.20			
Lead Thickness	С	0.35	0.35 0.40				
Lead 2 Width	b	0.41	0.41 0.50				
Leads 1 & 3 Width	b1	0.36	0.42	0.48			

## Notes:

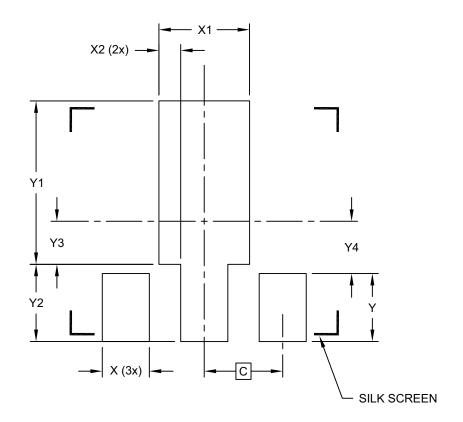
- 1. Dimensions D and E do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.127mm per side.
- 2. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing C04-029C Sheet 2 of 2

# 3-Lead Plastic Small Outline Transistor (MB) - [SOT-89]

**Note:** For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

Units	MILLIMETERS					
Dimension Limits	MIN	NOM	MAX			
С		1.50 (BSC)				
X		0.900				
X1		1.733				
X2		0.416				
Y		1.300				
Y1		4.600				
Y2		1.475				
Y3		0.950				
Y4		1.125				

## Notes:

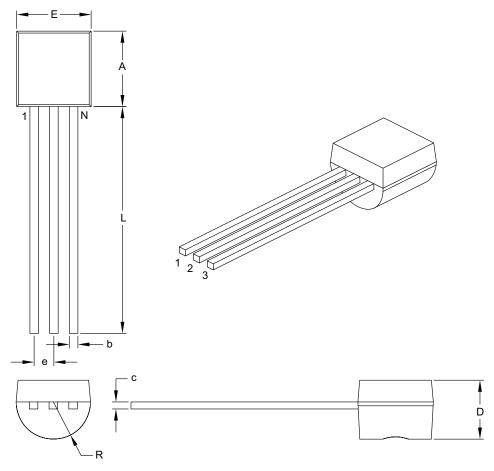
1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2029B

# 3-Lead Plastic Transistor Outline (ZB) [TO-92]

**Note:** For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



	Units			
Dimension	n Limits	MIN	MAX	
Number of Pins	N	3		
Pitch	е	.050 BSC		
Bottom to Package Flat	D	.125	.165	
Overall Width	Е	.175	.205	
Overall Length	Α	.170 .210		
Molded Package Radius	R	.080	.105	
Tip to Seating Plane	L	.500	_	
Lead Thickness	С	.014	.021	
Lead Width	b	.014	.022	

## Notes:

- 1. Dimensions A and E do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .005" per side.
- 2. Dimensioning and tolerancing per ASME Y14.5M.

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing C04-101B

## APPENDIX A: REVISION HISTORY

## **Revision K (July 2014)**

The following is the list of modifications:

1. Updated the "DC Characteristics" table.

## **Revision J (June 2011)**

The following is the list of modifications:

- Updated temperature values in the "Temperature Specifications" table.
- 2. Corrected equation in Figure 4-1.
- Added new examples layout in Section 5.1, Package Marking Information.

## **Revision H (December 2007)**

The following is the list of modifications:

- 1. Updated Features section.
- 2. Removed 5-Pin SOT-23 related information.
- 3. Updated Output Current (I<sub>OUT</sub>) Electrical Specification.
- 4. Removed 7.7V (typical) Voltage Trip Point Option. Max Trip Point Voltage is now 6.0V.
- 5. Updated Pin Function Table.
- 6. Updated Packaging Specification Information.
- 7. Added Revision History section.
- 8. Updated Product Identification System page.

## **Revision G (August 2004)**

Undocumented changes.

## Revision F (July 2004)

Undocumented changes.

## Revision E (April 2003)

Undocumented changes.

## **Revision D (October 2002)**

Undocumented changes.

## Revision C (July 2002)

Undocumented changes.

## Revision B (May 2002)

Undocumented changes.

## Revision A (March 2001)

Original Release of this Document.

# PRODUCT IDENTIFICATION SYSTEM

To order or obtain information, e.g., on pricing or delivery, refer to the factory or the listed sales office.

PART NO.	<u>X</u>	<u> </u>	<u>x</u> T	X	<u>X</u>	XX	<u>хх</u>	Exa	amples:	
		Detected Voltage	Extra	Tolerance			Taping Direction	a)	TC54VC1402ECB713:	Tape and Reel, 1.4V Voltage Detector, 2% Tol., SOT-23A-3
Device:		TC54V:	Voltage D	etector				b)	TC54VC1402EMB713:	Tape and Reel, 1.4V Voltage Detector, 2% Tol., SOT-89-3
Output Configuration:		N = N- C = CI	-Channel O MOS Outpu	pen-Drain t				c)	TC54VC1402EZB:	1.4V Voltage Detector, 2% Tol., TO-92
Detected Voltag	ge:	14 = 1. 21 = 2. 27 = 2.	1V					d)	TC54VC2102ECB713:	Tape and Reel, 2.1V Voltage Detector, 2% Tol., SOT-23A-3
		29 = 2. 30 = 3. 42 = 4. 43 = 4.	0V 2V					e)	TC54VC2102EMB713:	Tape and Reel, 2.1V Voltage Detector, 2% Tol., SOT-89-3
Extra Feature C	Code:	0 = Fi	xed					f)	TC54VC2102EZB:	2.1V Voltage Detector, 2% Tol., TO-92
Tolerance:		2 = 2%	%					g)	TC54VC2702ECB713:	Tape and Reel, 2.7V Voltage Detector, 2% Tol., SOT-23A-3
Temperature:		E = -4	40°C to +85	°C				h)	TC54VC3002ECB713:	Tape and Reel, 3.0V Voltage Detector, 2% Tol., SOT-23A-3
Package:		MB = PI	astic Small	Outline Trans Outline Trans stor Outline,	istor, SO	T-89, 3		i)	TC54VN4202ECB713:	Tape and Reel, 4.2V Voltage Detector, 2% Tol., SOT-23A-3
Taping Directio	n:	713 = S	tandard Tap	oing						

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